



Material Content Data Sheet



Sales Product Name	TLE75620-EST			Issued	1. August 2018			
MA#	MA001709738							
Package	PG-TSDSO-24-21			Weight*	796.89 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.094	0.39	0.39	3882	3882
leadframe	inorganic material	phosphorus	7723-14-0	0.064	0.01		80	
	non noble metal	zinc	7440-66-6	0.256	0.03		321	
	non noble metal	iron	7439-89-6	5.116	0.64		6421	
wire	non noble metal	copper	7440-50-8	207.751	26.07	26.75	260703	267525
	non noble metal	copper	7440-50-8	0.940	0.12	0.12	1180	1180
	encapsulation	organic material	carbon black	1333-86-4	1.724	0.22		2163
encapsulation	plastics	epoxy resin	-	67.228	8.44		84363	
	inorganic material	silicondioxide	60676-86-0	505.646	63.45	72.11	634525	721051
leadfinish	non noble metal	tin	7440-31-5	3.642	0.46	0.46	4571	4571
plating	noble metal	silver	7440-22-4	0.339	0.04	0.04	425	425
glue	plastics	epoxy resin	-	0.190	0.02		239	
	noble metal	silver	7440-22-4	0.898	0.11	0.13	1127	1366
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com